

Solid State RF Power

The Route to 1W per Euro Cent

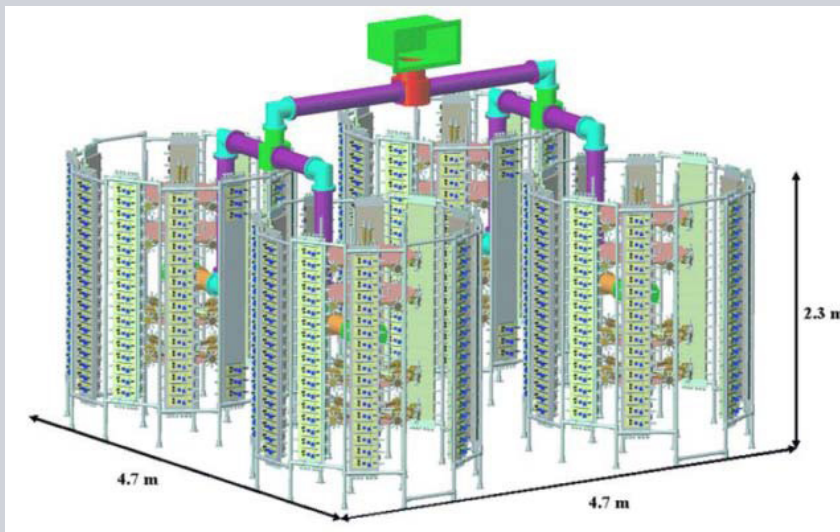
Oliver Heid

Corporate Technologies

Siemens AG, Munich

Design of Solid State Amplifiers Today

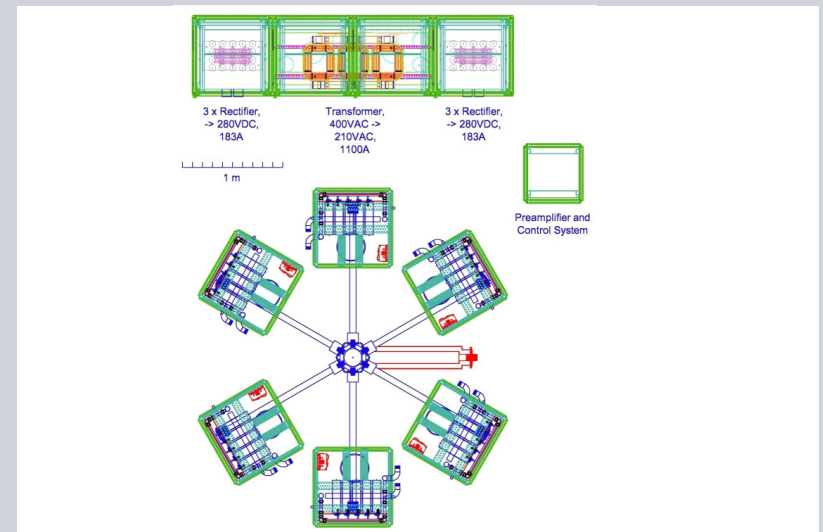
190 kW SOLEIL Solid State Amplifier



POLYFET Si LDMOS (LR301),
682 modules x 1 transistor,
315 W power each

J. Jacob, WEXPA02, Proceedings of EPAC 2006, Edinburgh, Scotland

CRE312 - 72 MHz 150 kW Solid State Cyclotron Amplifier



Si VDMOS transistors,
6x2x10x4 combiner tree
~400 W each

M. Getta et al. TU5PFP081 Proceedings of PAC09,
Vancouver, BC, Canada

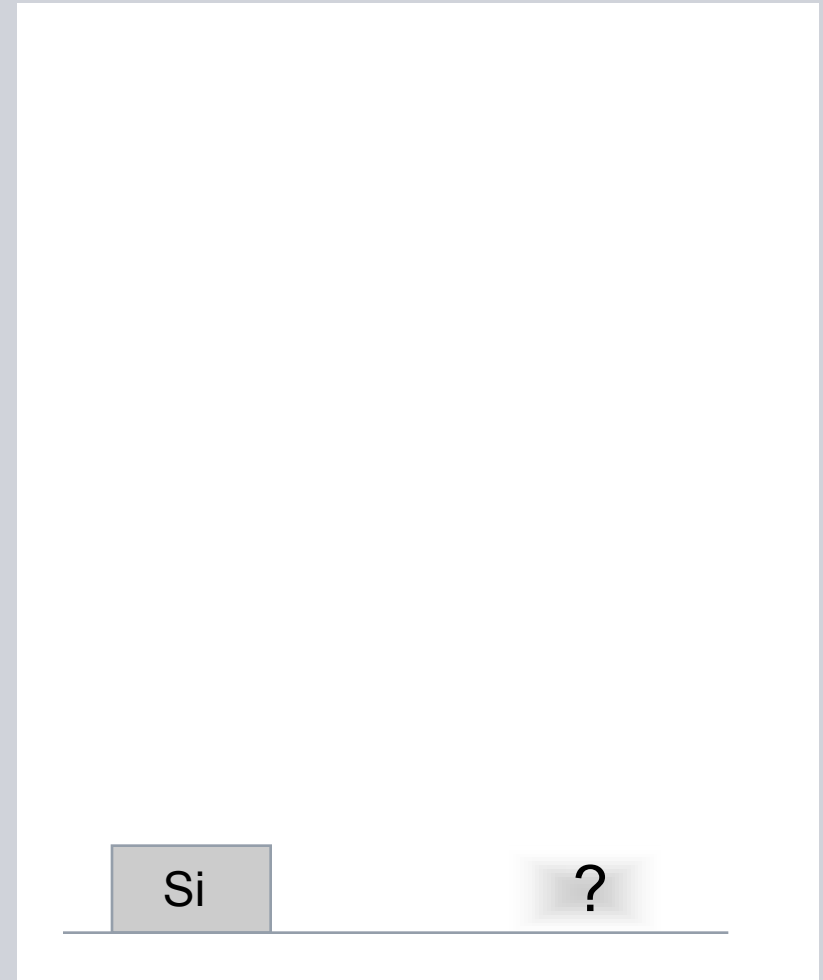
Cost position?

Cost position

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Cost position?

Switch from Si to wide bandgap semiconductors



Cost position?

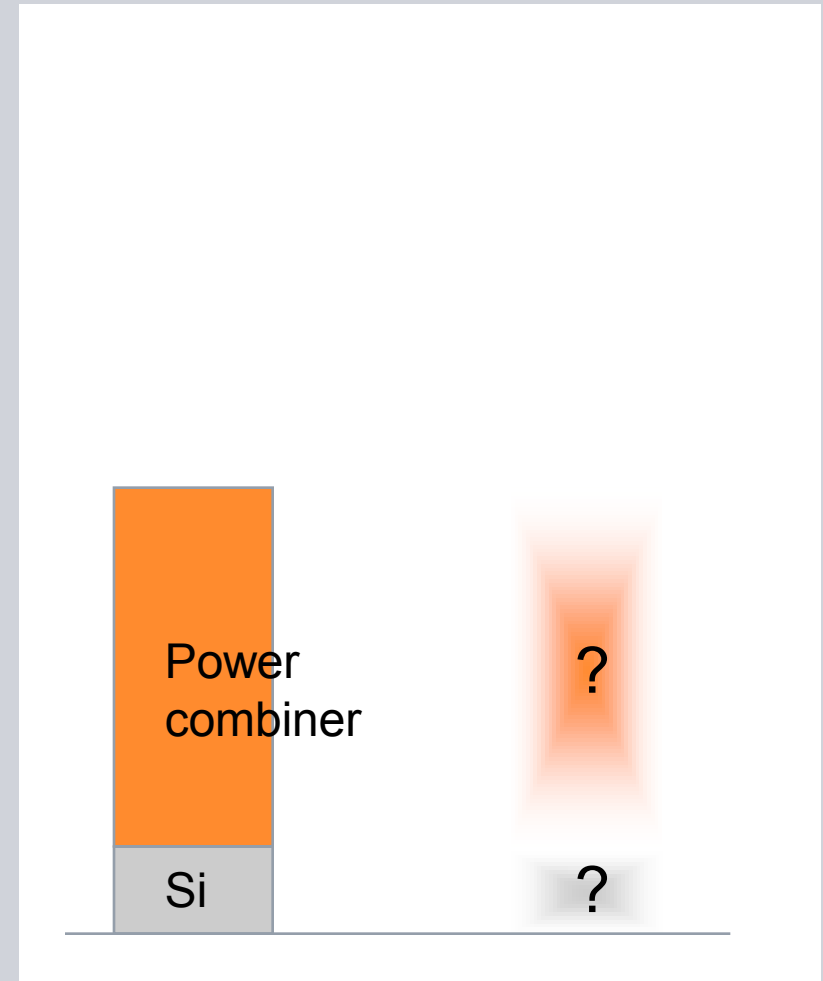
Switch from Si to wide bandgap semiconductors

Complexity

Modular approach

Herd of Elephants vs Army of Ants

Single stage RF power combiner



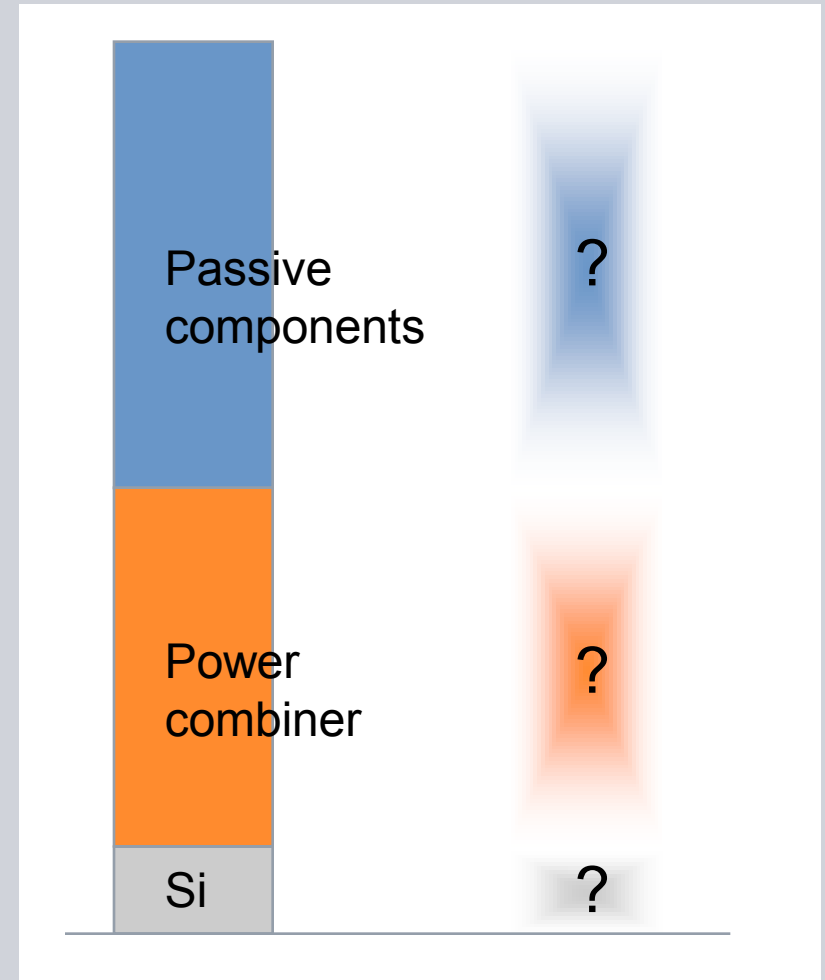
Cost position?

Switch from Si to wide bandgap semiconductors

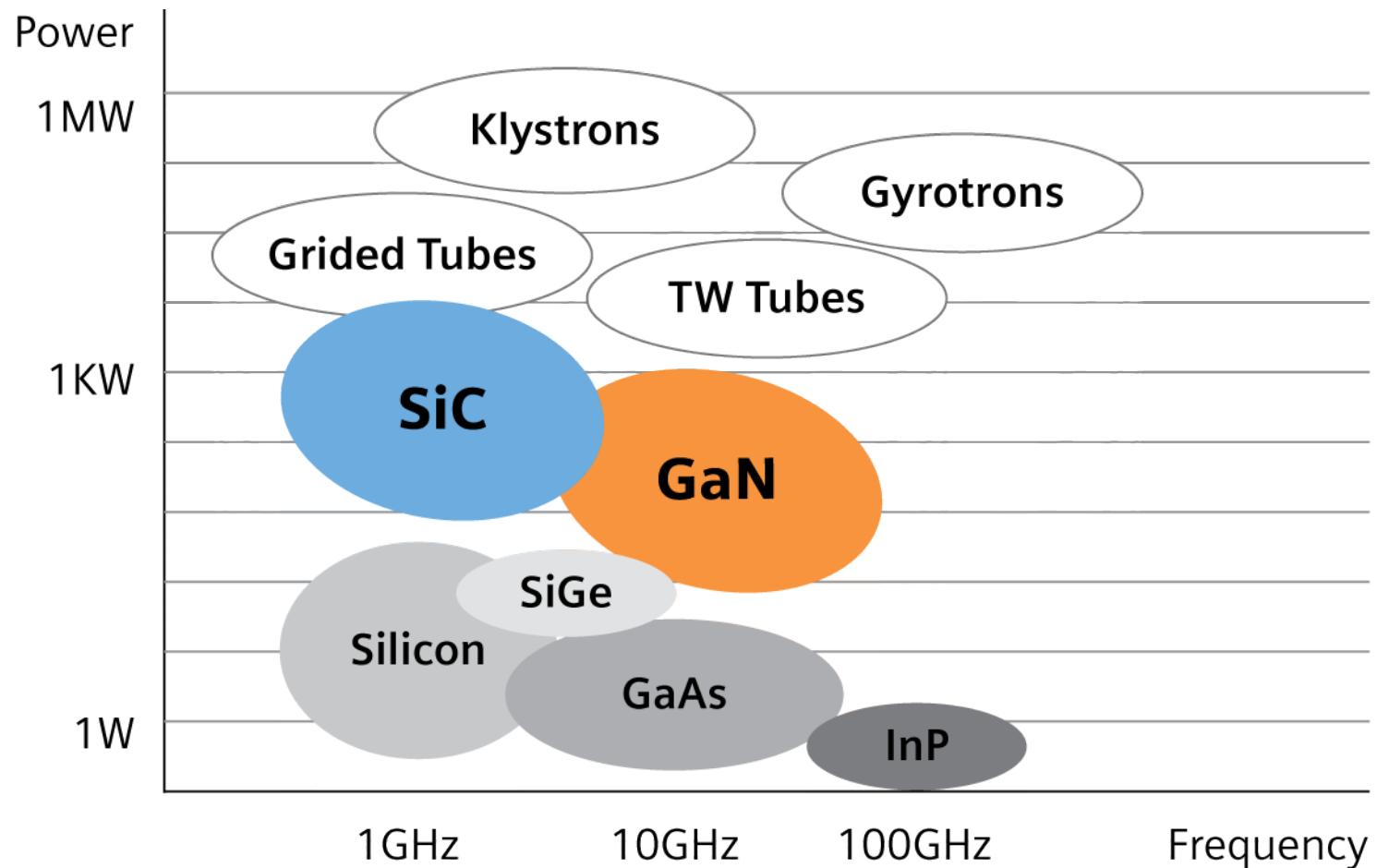
Herd of Elephants instead of Army of Ants modular approach

Single stage RF power combiner

Minimal use of specialized passive components: economics of scale

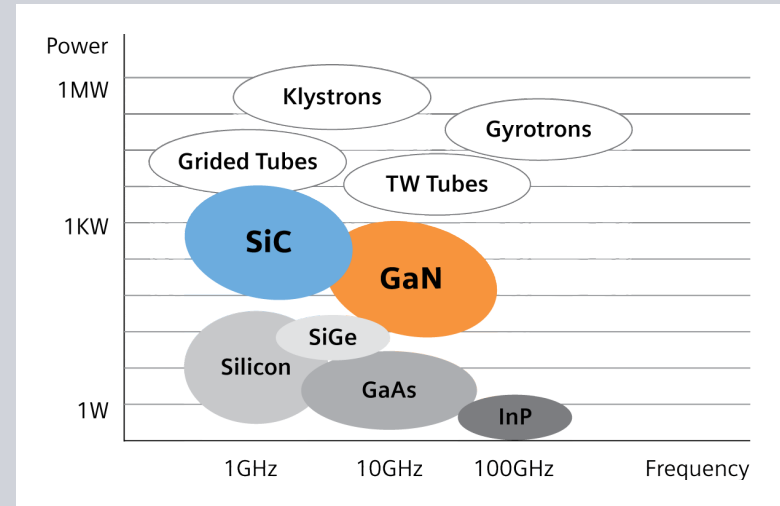


RF Power Devices – State of the Art



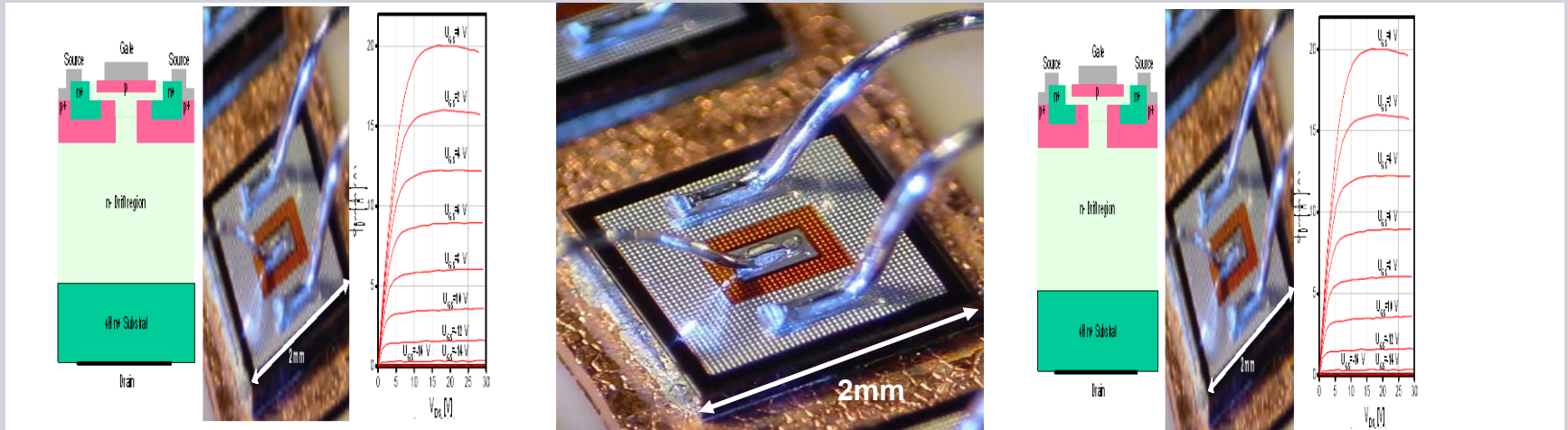
Wide Bandgap RF Semiconductors

- SiC intrinsically 10x faster than silicon
- Significantly enhanced power density
- Radiation hardened
- High heat conductivity



Materials Property	Si	SiC-4H	GaN
Band Gap [eV]	1.1	3.2	3.4
Critical Field [MV/m]	30	300	350
Electron Mobility [cm ² /(Vs)]	1450	900	2000
Electron Saturation Velocity [km/s]	100	220	250
Thermal Conductivity [W/cm ² K]	1.5	5	1.3

SiC RF Power vJFET



Normally on vertical junction FET (vJFET) with intrinsic body diode
 Based on commercial switch mode PSU power transistor design
 Optimized for low gate series impedance

2.4x2.4mm² die size

$U_{DS} = 1700V$, $I_{DSS} = 60A$

$U_{pinchoff} \sim -16V$

SiC RF Power vJFET

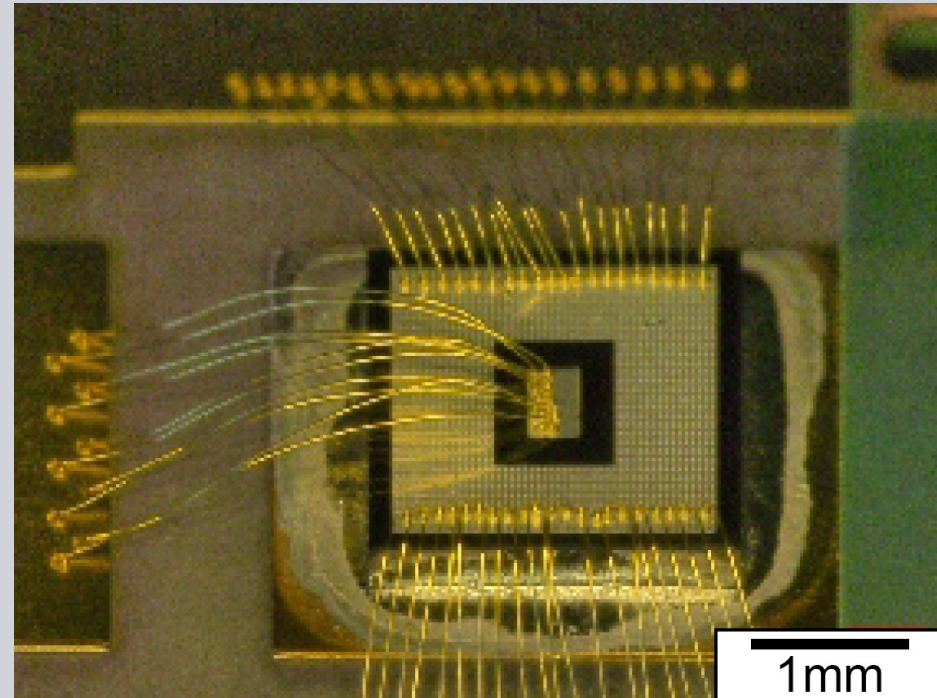
High efficiency (>85%)
Class F mode operation

Hyperfast Schottky-like body diode
enables four quadrant operation
Reflected RF power does not destruct
device

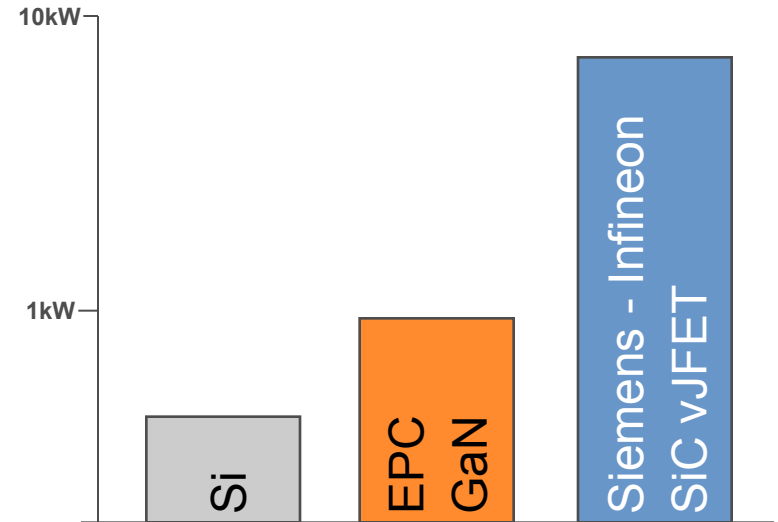
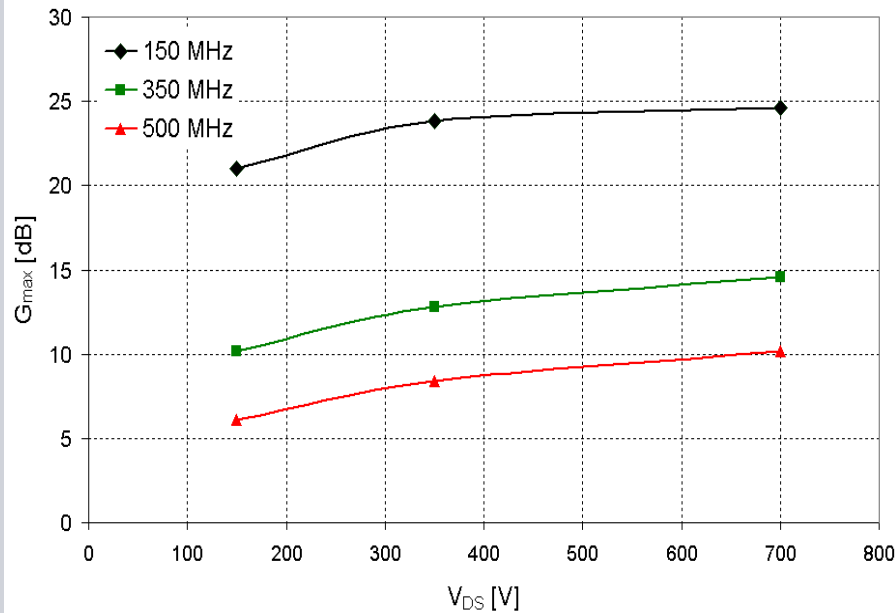
No output circulators, protection
measures needed

“Voltage source” low output impedance
operation, no need to match RF load

High voltage operation (~700VDC)
enables extremely high power at
reasonable impedances



Current Status



SiC 6mm² die

7 kW_{pk} (200μs burst)

~ 1 GHz unity gain frequency

GaN 1.5mm² die

250 W_{pk} (200μs burst)

~ 2 GHz unity gain frequency

SiC RF Power Modules

Parallel push-pull circuit assists class F operation

Stable under load impedance variations, device parallelization

8 transistors per module

On 60x80mm² Al₂O₃ carrier

SiPLiT package: no bond wires

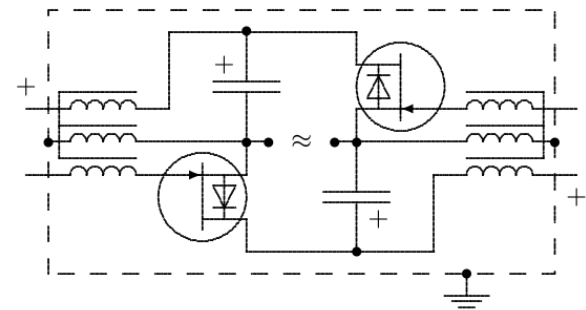
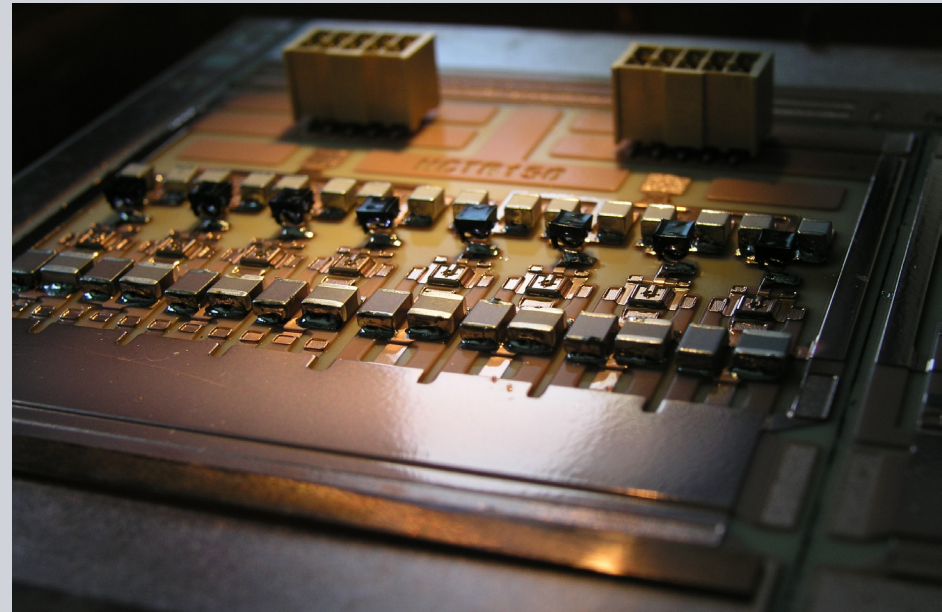
Commodity 700V DC supply

50 kW RF pulse power into 5Ω:

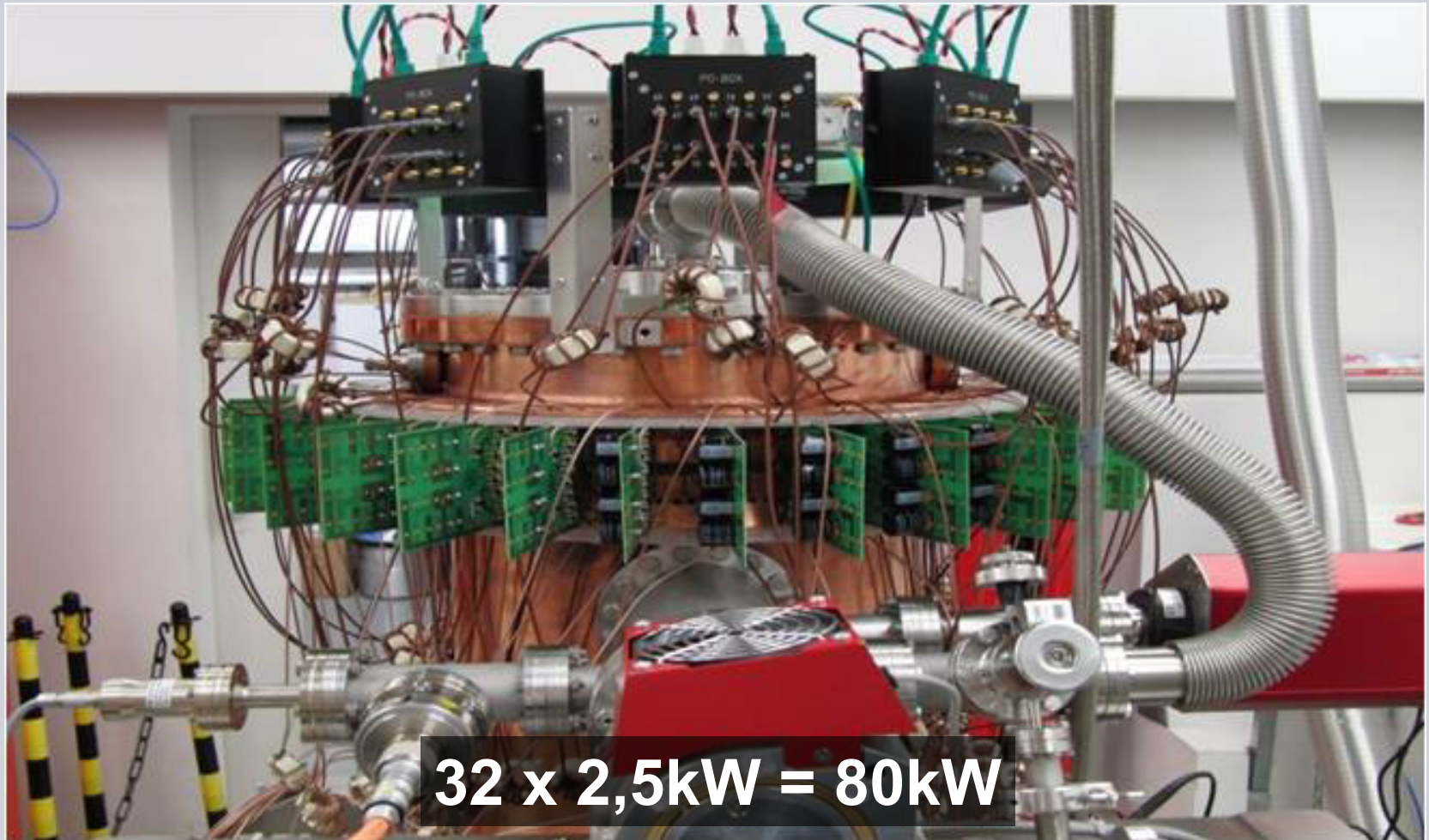
700V_{pk}, 140A_{pk}

200 μs pulse duration, 1% dc

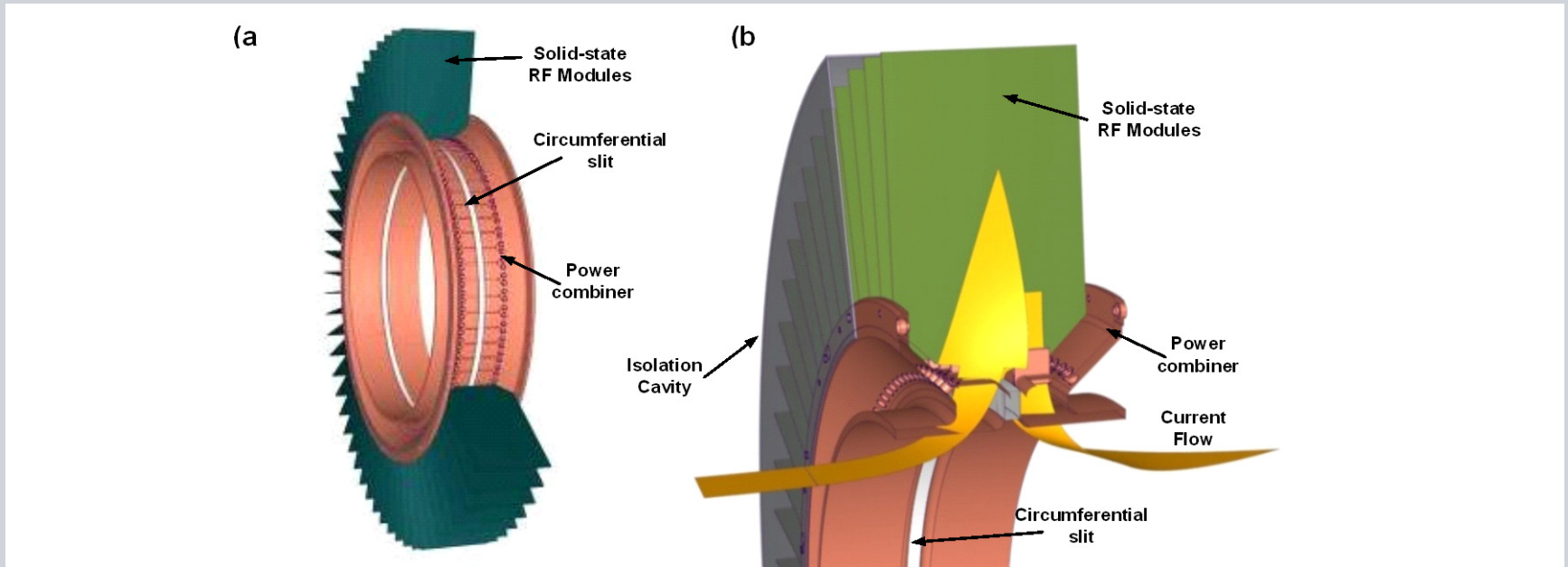
15dB large signal power gain



RF Power Combiner Teststand



RF Power Combiner: Solid State Direct Drive™



- Much higher power levels possible by single stage combiner
- Low output impedance gives very low combined power reduction under point failures: reliability

Cost Position

Minimal complexity

- High power density, power per device: low device count, low circuit complexity
- Straightforward single stage power combining, no power circulators, protection circuits
- RF power gating within amplifier stage: Simple DC power supply

Economics of scale

- Bulk SiC, epitaxial GaN and Si have similar material and production cost per Watt RF
- Voltages, currents within range of standard consumer/industrial component specs
- Modular design covers diverse customer requirements with few module designs

“green”, dependable

- High efficiency class F operation: low thermal load, energy costs
- Gracefully degrading RF power generator under point failures: preventive maintenance

Conclusions

1 Watt / Euro Cent

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Conclusions

1 Watt per Euro Cent seems to be within reach

SiC and GaN are about cost competitive with Si



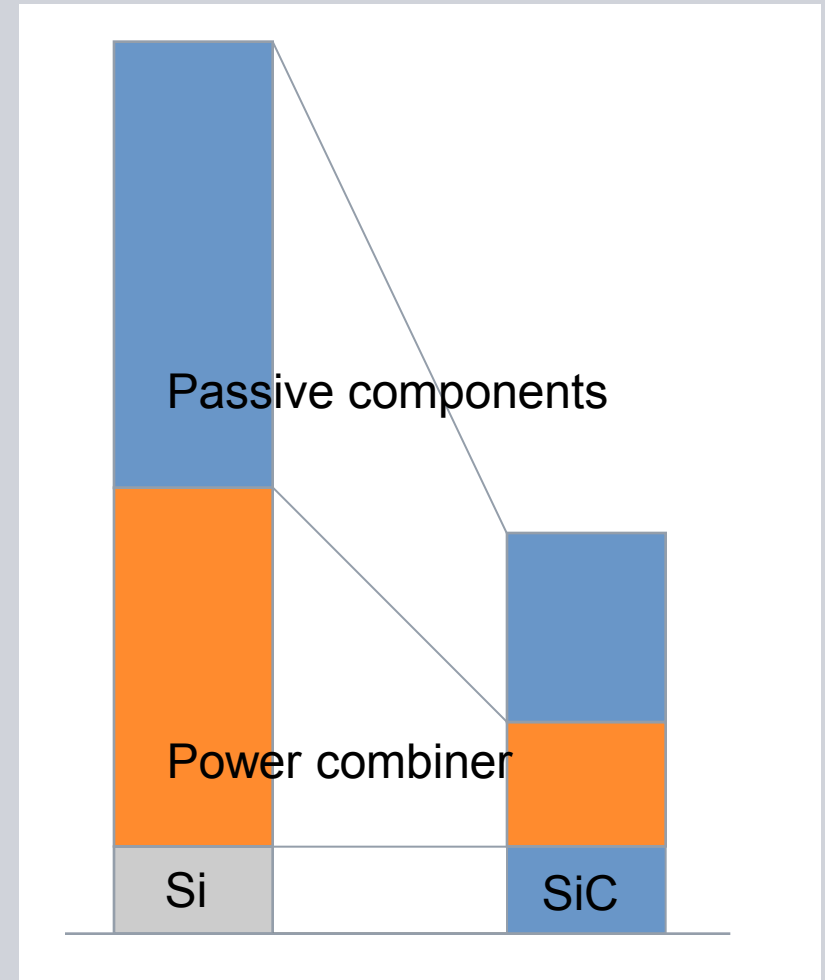
Conclusions

1 Watt per Euro Cent seems to be within reach

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BUT

The big win is its secondary effects on the system complexity and cost



Thank you for your attention!

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